11.3-Gbps Limiting Amplifier

FEATURES

- **Up to 11.3-Gbps Operation**
- **Loss-of-Signal Detection (LOS)**
- **Adjustable Output Voltage**
- **Low Power Consumption**
- **Input Offset Cancellation**
- **CML Data Outputs With On-Chip, 50-Ω Back-Termination to VCC**
- **Single 3.3 V Supply**
- **Surface-Mount, Small-Footprint, 3-mm × 3-mm, 16-Pin QFN Package**

APPLICATIONS

- **10 Gigabit Ethernet Optical Transmitters**
- **8× and 10× Fibre Channel Optical Transmitters**
- **SONET OC-192/SDH-64 Optical Transmitters**
- **XFP and SFP+ Transceiver Modules**
- **XENPAK, XPAK, X2 and 300-Pin MSA Transponder Modules**
- **Cable Driver and Receiver**

DESCRIPTION

The ONET1191P is a high-speed, 3.3-V limiting amplifier for copper-cable and fiber-optic applications with data rates up to 11.3 Gbps.

This device provides a gain of about 40 dB which ensures a fully differential output swing for input signals as low as 5 mV_{pp}. The output amplitude can be adjusted from 400 mV_{pp} to 700 mV_{pp}. Loss-of-signal detection and output disable are also provided.

The part is available in a small-footprint, 3-mm × 3-mm, 16-pin QFN package, typically dissipates less than 110 mW, and is characterized for operation from –40°C to 85°C.

Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of the Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

Copyright © 2006, Texas Instruments Incorporated

BLOCK DIAGRAM

A simplified block diagram of the ONET1191P is shown in Figure 1.

This compact, low-power, 11.3-Gbps limiting amplifier consists of a high-speed data path with offset cancellation (dc feedback), a loss-of-signal detection block using two peak detectors, and a band-gap voltage reference and bias current generation block.

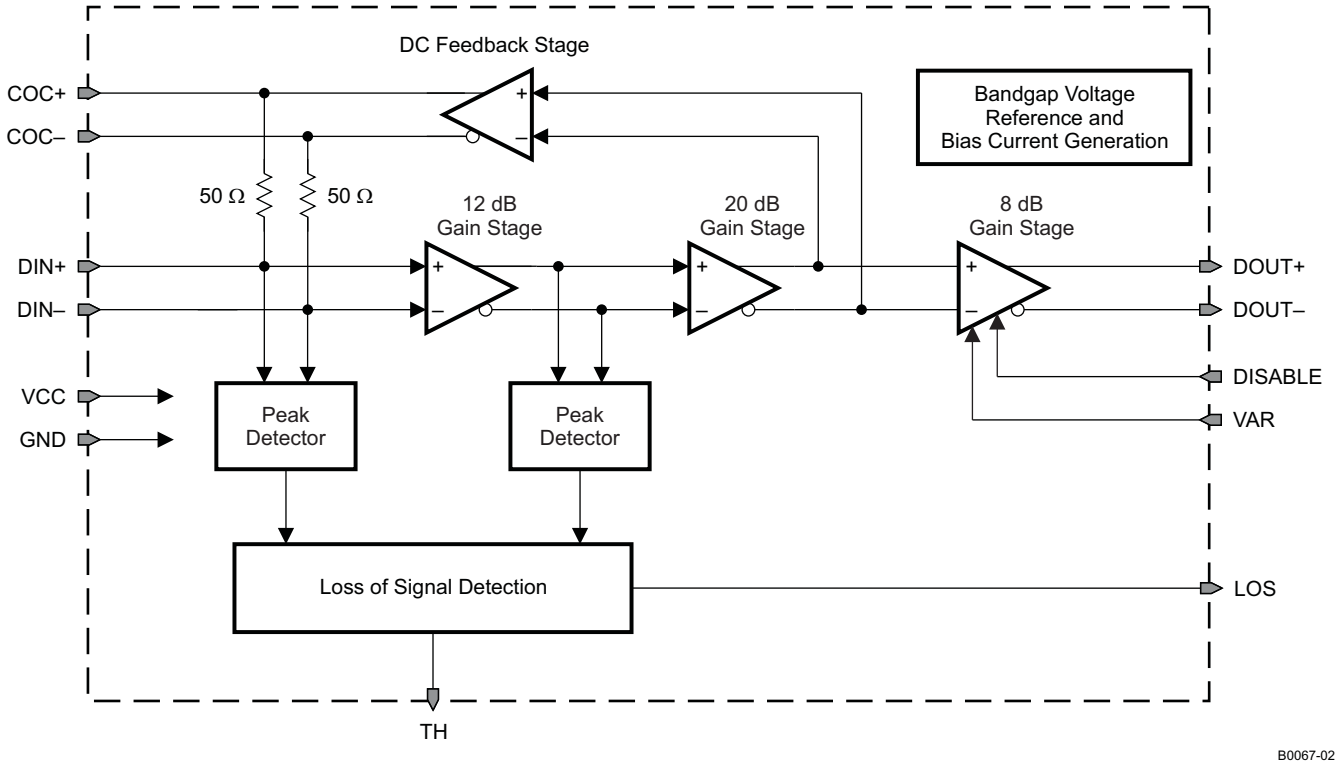


Figure 1. Simplified Block Diagram of the ONET1191P

HIGH-SPEED DATA PATH

The high-speed data signal is applied to the data path by means of the input signal pins, DIN+/DIN–. The data path consists of a 12-dB input gain stage with 2 × 50-Ω on-chip line-termination resistors, a second gain stage with 20 dB of gain, and a variable-gain output stage which provides another 8 dB of gain. The amplified data output signal is available at the output pins DOUT+/DOUT–, which include on-chip 2 × 50-Ω back-termination to VCC. The output amplitude can be adjusted between 400 mV_{pp} and 700 mV_{pp} by connecting an external resistor between the VAR pin and ground (GND).

A dc feedback stage compensates for internal offset voltages and thus ensures proper operation even for very small input data signals. This stage is driven by the output signal of the second gain stage. The signal is low-pass filtered, amplified, and fed back to the input of the first gain stage via the on-chip, 50-Ω termination resistors. The required low-frequency cutoff is determined by an external 0.1 µF capacitor, which must be differentially connected to the COC+/COC– pins.

LOSS-OF-SIGNAL DETECTION

The peak values of the input signal and output signal of the first gain stage are monitored by two peak detectors. The peak values are compared to a predefined loss-of-signal threshold voltage inside the loss-of-signal detection block. As a result of the comparison, the LOS signal, which indicates that the input signal amplitude is below the defined threshold level, is generated.

The threshold voltage can be set within a certain range by means of an external resistor connected between the TH pin and ground.

BAND-GAP VOLTAGE AND BIAS GENERATION

The ONET1191P limiting amplifier is supplied by a single 3.3-V supply voltage connected to the VCC pins. This voltage is referred to ground (GND).

On-chip band-gap voltage circuitry generates a reference voltage, independent of supply voltage, from which all other internally required voltages and bias currents are derived.

PACKAGE

For the ONET1191P, a small-footprint, 3-mm × 3-mm, 16-pin QFN package, with a lead pitch of 0,5 mm, is used. The pinout is shown in Figure 2.

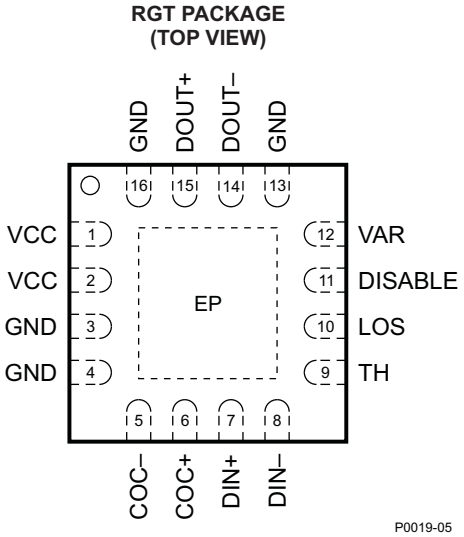


Figure 2. Pinout of ONET1191P in a 3-mm × 3-mm, 16-Pin QFN Package

TERMINAL FUNCTIONS

TERMINAL		TYPE	DESCRIPTION
NAME	NO.		
COC+	6	Analog	Offset cancellation filter capacitor plus terminal. An external 0.1 µF filter capacitor must be connected between this pin and COC– (pin 5).
COC–	5	Analog	Offset cancellation filter capacitor minus terminal. An external 0.1 µF filter capacitor must be connected between this pin and COC+ (pin 6).
DIN+	7	Analog input	Noninverted data input. On-chip, 50-Ω terminated to COC+. Differentially 100-Ω terminated to DIN–.
DIN–	8	Analog input	Inverted data input. On-chip, 50-Ω terminated to COC–. Differentially 100-Ω terminated to DIN+.
DISABLE	11	CMOS input	Disables the output stage when set to a high level
DOUT+	15	CML out	Noninverted data output. On-chip, 50-Ω back-terminated to VCC.
DOUT–	14	CML out	Inverted data output. On-chip, 50-Ω back-terminated to VCC.
GND	3, 4, 13, 16, EP	Supply	Circuit ground. Exposed die pad (EP) must be grounded.
LOS	10	Open-drain MOS	High level indicates that the input signal amplitude is below the programmed threshold level. Open-drain output. Requires an external 10-kΩ pullup resistor to VCC for proper operation.
TH	9	Analog input	LOS threshold adjustment with resistor to GND
VAR	12	Analog input	Variable output amplitude control. Output amplitude can be reduced to 400 mV_{pp} by grounding the VAR pin. Output amplitude can be set from 400 mV_{pp} to 700 mV_{pp} by connecting a 0 to 100-kΩ resistor to GND or leaving the pin open.
VCC	1, 2	Supply	3.3-V ±10% supply voltage

ABSOLUTE MAXIMUM RATINGS

over operating free-air temperature range (unless otherwise noted)(1)

		VALUE	UNIT
V_{CC}	Supply voltage(2)	–0.3 to 4	V
V_{DIN+}, $V_{DIN–}$	Voltage at DIN+, DIN–(2)	0.5 to 4	V
V_{LOS}, V_{COC+}, $V_{COC–}$, V_{TH}, V_{DOUT+}, $V_{DOUT–}$	Voltage at LOS, COC+, COC–, TH, DOUT+, DOUT–(2)	–0.3 to 4	V
$V_{DIN,DIFF}$	Differential voltage between DIN+ and DIN–	±1.25	V
I_{LOS}	Current into LOS	1	mA
I_{DIN+}, $I_{DIN–}$, I_{DOUT+}, $I_{DOUT–}$	Continuous current at inputs and outputs	20	mA
ESD	ESD rating at all pins	1.5	kV (HBM)
$T_{J,max}$	Maximum junction temperature	125	°C
T_{STG}	Storage temperature range	–65 to 85	°C
T_A	Characterized free-air operating temperature range	–40 to 85	°C
T_{LEAD}	Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	260	°C

(1) Stresses beyond those listed under *absolute maximum ratings* may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under *recommended operating conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
(2) All voltage values are with respect to network ground terminal.

RECOMMENDED OPERATING CONDITIONS

		MIN	TYP	MAX	UNIT
V_{CC}	Supply voltage	2.9	3.3	3.6	V
T_A	Operating free-air temperature	–40		85	°C
	Disable input high voltage	2			V
	Disable input low voltage			0.25	V
	Optimum LOS threshold resistor	32		62	kΩ
	R_{VAR} range	0		open	kΩ

DC ELECTRICAL CHARACTERISTICS

over recommended operating conditions, outputs connected to a 50-Ω load, R_{VAR} = open (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
V_{CC}	Supply voltage		2.9	3.3	3.6	V
I_{VCC}	Supply current	DISABLE = LOW		33	49	mA
R_{IN}	Data input resistance	Single-ended to COC pins		50		Ω
R_{OUT}	Data output resistance	Single-ended, referenced to V_{CC}		50		Ω
	Voltage at TH pin			1.25		V
	LOS HIGH voltage	10-kΩ pullup to V_{CC}, I_{SOURCE} = 50 µA	2.4			
	LOS LOW voltage	10-kΩ pullup to V_{CC}, I_{SINK} = 200 µA			0.5	V

AC ELECTRICAL CHARACTERISTICS

over recommended operating conditions, outputs connected to a 50-Ω load, R_{VAR} = open (unless otherwise noted). Typical operating condition is at V_{CC} = 3.3 V and T_A = 25°C.

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
f_{3dB-H}	High-frequency –3-dB bandwidth		8	11	15	GHz
f_{3dB-L}	Low-frequency –3-dB bandwidth	C_{OC} = 0.1 µF, ac coupling capacitors = 0.1 µF		30		kHz
$v_{IN,MIN}$	Data input sensitivity	K28.5 at 11.3 Gbps, BER < 10^{-12}		2.5	5	mV_{pp}
		$V_{OD-min} \geq 0.95 \times V_{OD}$ (output limited)		10	20	
A	Small-signal gain		34	40	44	dB
$V_{IN,MAX}$	Data input overload		2000			mV_{pp}
DJ	Deterministic jitter	V_{IN} = 5 mV_{pp}, K28.5 at 11.3 Gbps		4	7	ps_{pp}
		V_{IN} = 20 mV_{pp}, K28.5 at 11.3 Gbps		4	9	
RJ	Random jitter	Input = 5 mV_{pp}		1.6		ps_{RMS}
		Input = 20 mV_{pp}		0.7		
V_{OD}	Differential data output voltage	$V_{IN} \geq$ 20 mV_{pp}, DISABLE = LOW	600	700	900	mV_{pp}
		DISABLE = HIGH		25	100	
t_r	Output rise time	20% to 80%, $V_{IN} \geq$ 20 mV_{PP}		25	35	ps
t_f	Output fall time	20% to 80%, $V_{IN} \geq$ 20 mV_{PP}		25	35	ps
V_{TH}	LOS assert threshold range	K28.5 pattern at 10.7 Gbps, R_{TH} = 62 kΩ		40		mV_{pp}
		K28.5 pattern at 10.7 Gbps, R_{TH} = 32 kΩ		65		
	LOS threshold variation	Versus temperature		3		dB
		Versus supply voltage V_{CC}		1		dB
	LOS hysteresis	K28.5 pattern at 11.3 Gbps	1.5		7	dB
t_{LOS_AST}	LOS assert time			1300	2000	ns
$t_{LOS,\ DEA_}$	LOS deassert time			120		ns
t_{DIS}	Disable response time			90		ns

TYPICAL OPERATION CHARACTERISTICS

Typical operating condition is at V_{CC} = 3.3 V, T_A = 25°C, and R_{VAR} = open (unless otherwise noted)

FREQUENCY RESPONSE

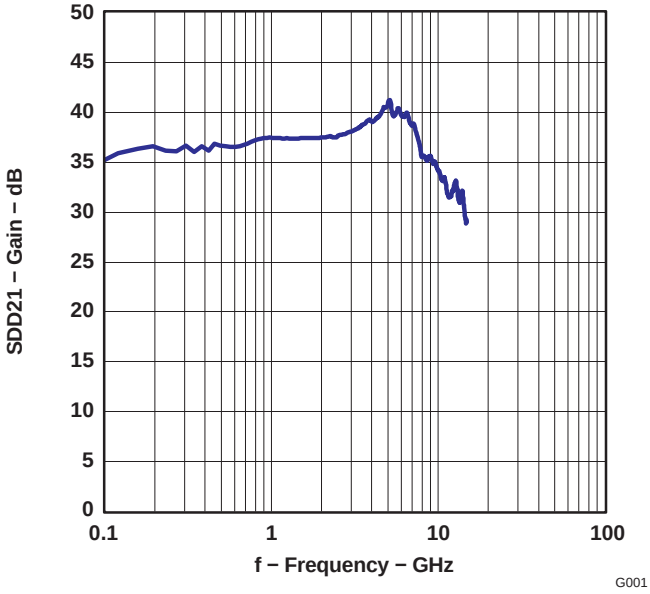


Figure 3.

TRANSFER FUNCTION

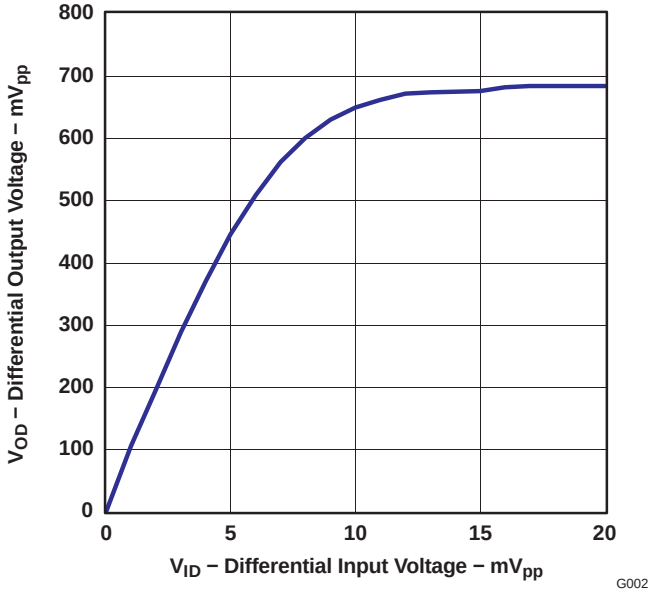


Figure 4.

DIFFERENTIAL INPUT RETURN GAIN
vs
FREQUENCY

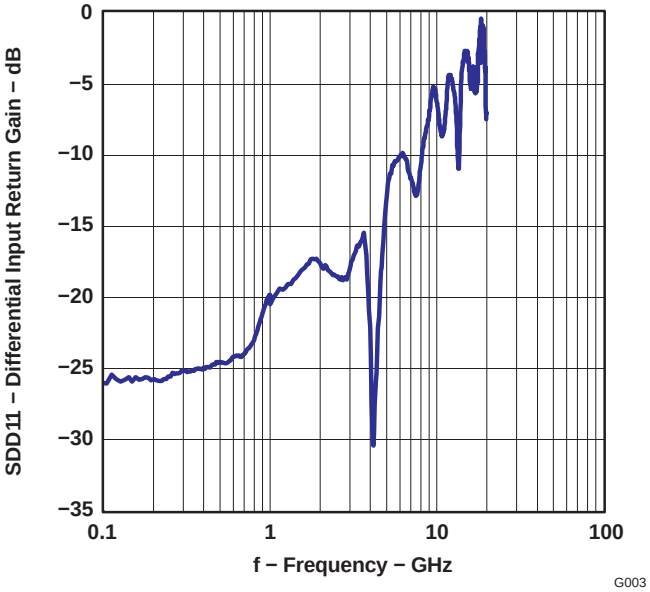


Figure 5.

DIFFERENTIAL OUTPUT RETURN GAIN
vs
FREQUENCY

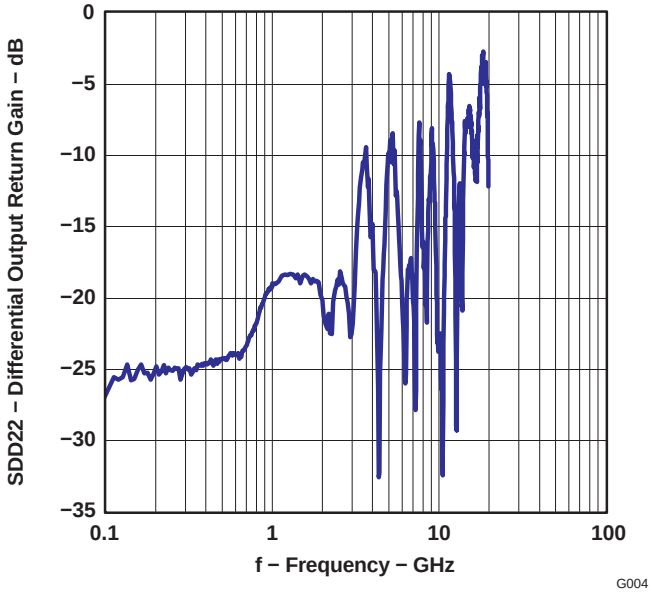


Figure 6.

TYPICAL OPERATION CHARACTERISTICS (continued)

Typical operating condition is at V_{CC} = 3.3 V, T_A = 25°C, and R_{VAR} = open (unless otherwise noted)

BIT-ERROR RATIO vs INPUT AMPLITUDE (11.3 GBPS)

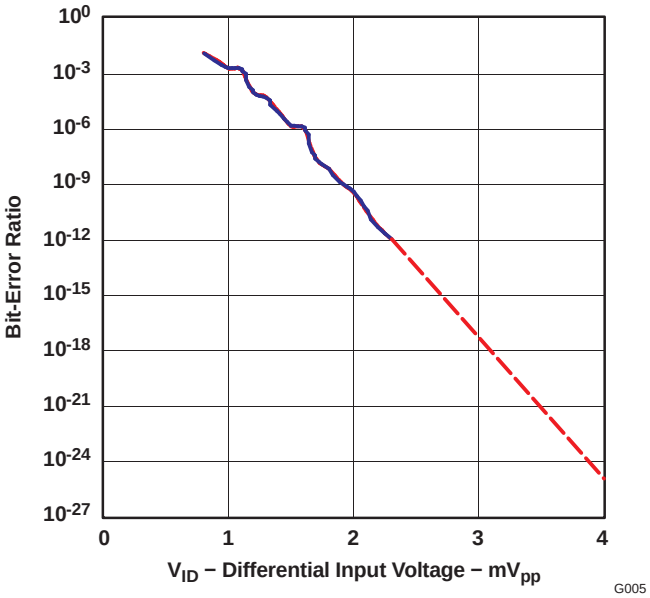


Figure 7.

DETERMINISTIC JITTER vs INPUT AMPLITUDE

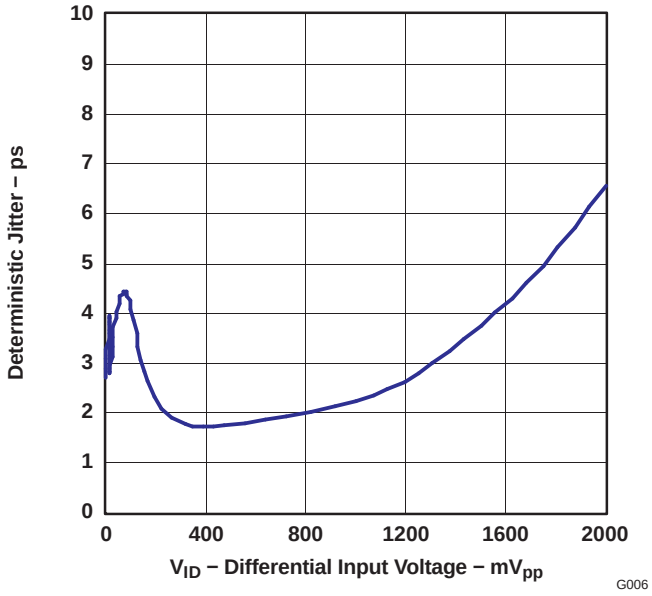


Figure 8.

RANDOM JITTER vs INPUT AMPLITUDE

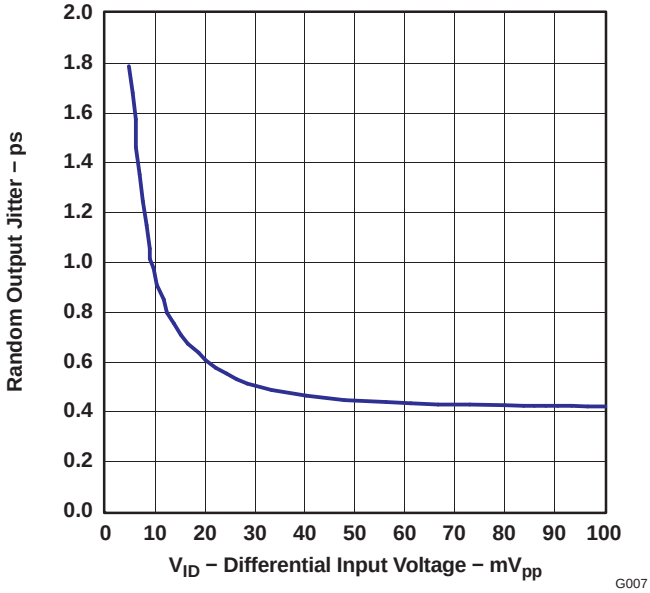


Figure 9.

LOS ASSERT/DEASSERT VOLTAGE vs THRESHOLD RESISTANCE

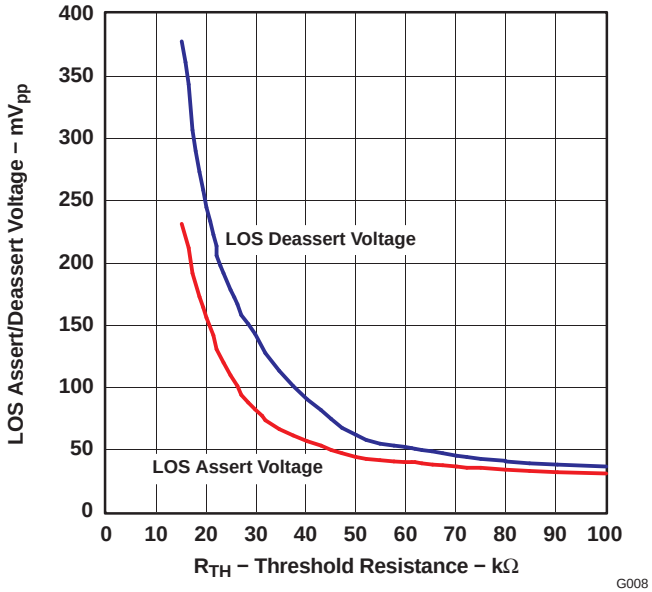


Figure 10.

TYPICAL OPERATION CHARACTERISTICS (continued)

Typical operating condition is at V_{CC} = 3.3 V, T_A = 25°C, and R_{VAR} = open (unless otherwise noted)

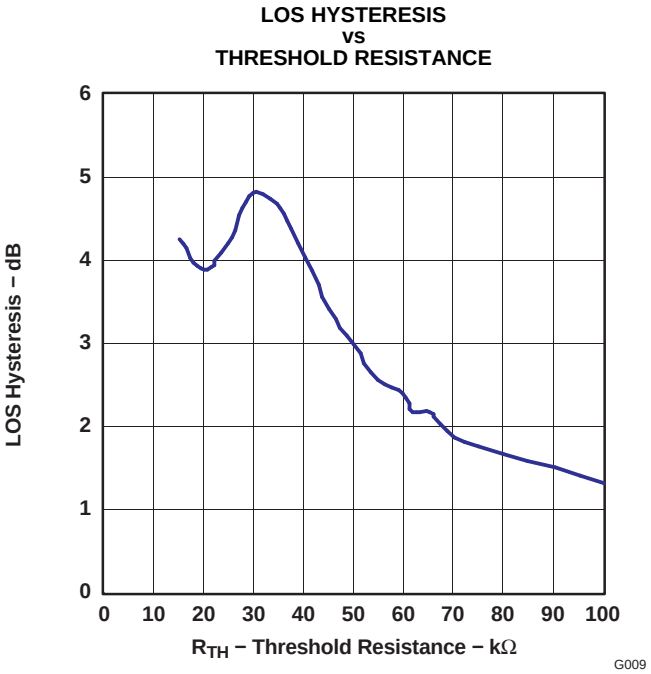


Figure 11.

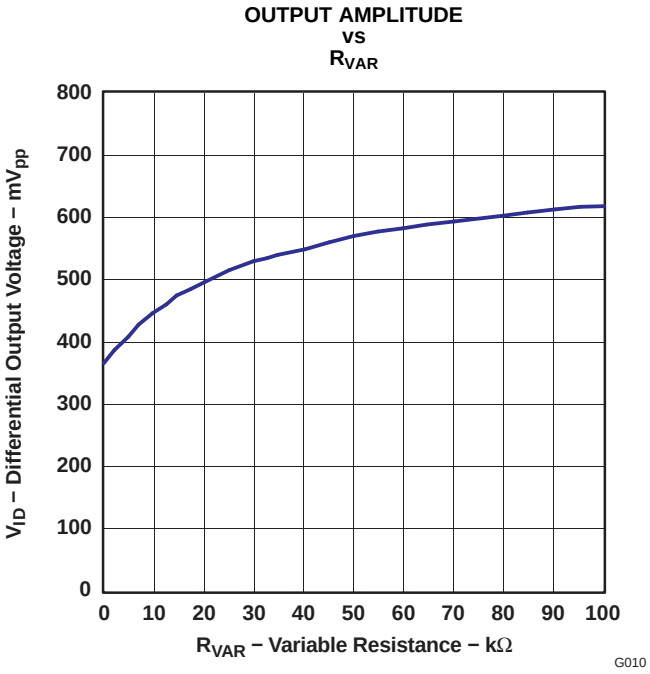


Figure 12.

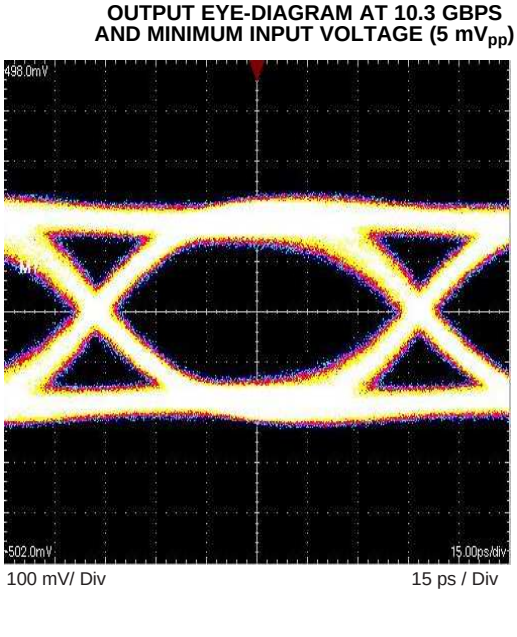


Figure 13.

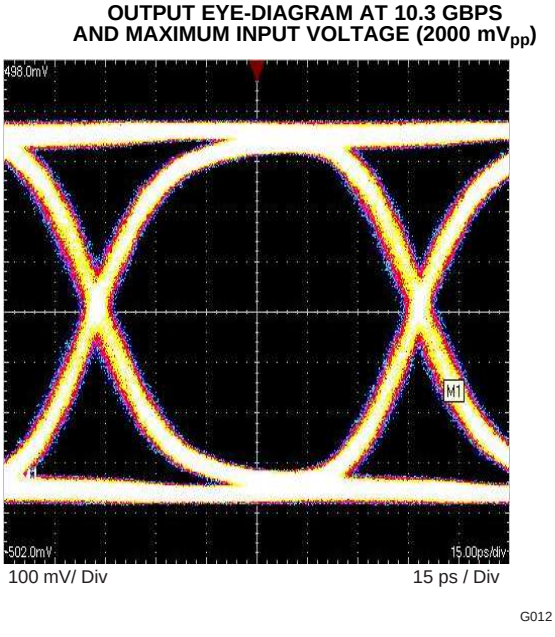


Figure 14.

TYPICAL OPERATION CHARACTERISTICS (continued)

Typical operating condition is at V_{CC} = 3.3 V, T_A = 25°C, and R_{VAR} = open (unless otherwise noted)

OUTPUT EYE-DIAGRAM AT 8.5 GBPS AND MINIMUM INPUT VOLTAGE (5 mV_{pp})

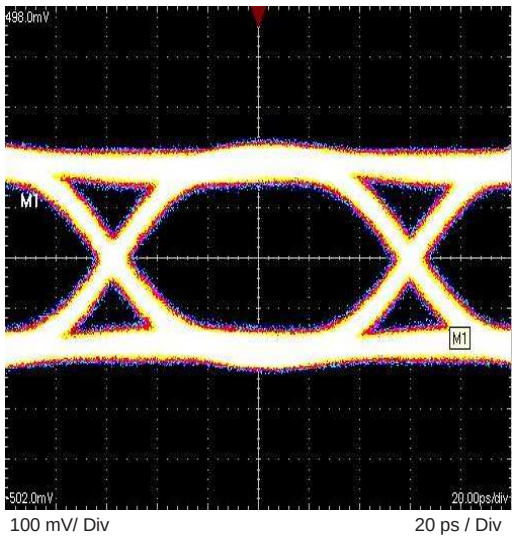


Figure 15.

OUTPUT EYE-DIAGRAM AT 8.5 GBPS AND MAXIMUM INPUT VOLTAGE (2000 mV_{pp})

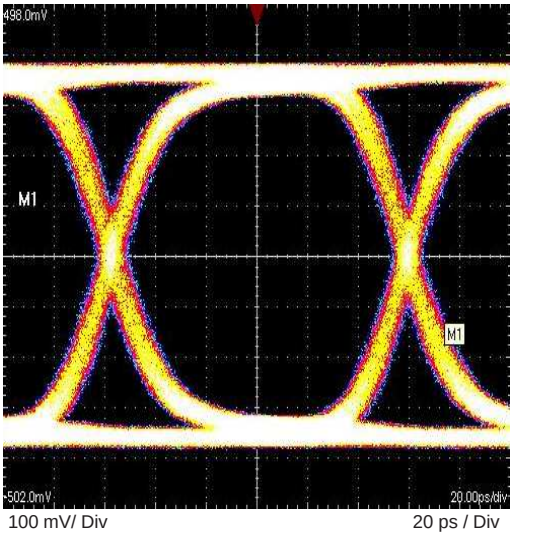


Figure 16.

APPLICATION INFORMATION

Figure 17 shows a typical application circuit using the ONET1191P. The output amplitude can be adjusted with R_{VAR} and the LOS assert voltage is adjusted with R_{TH}.

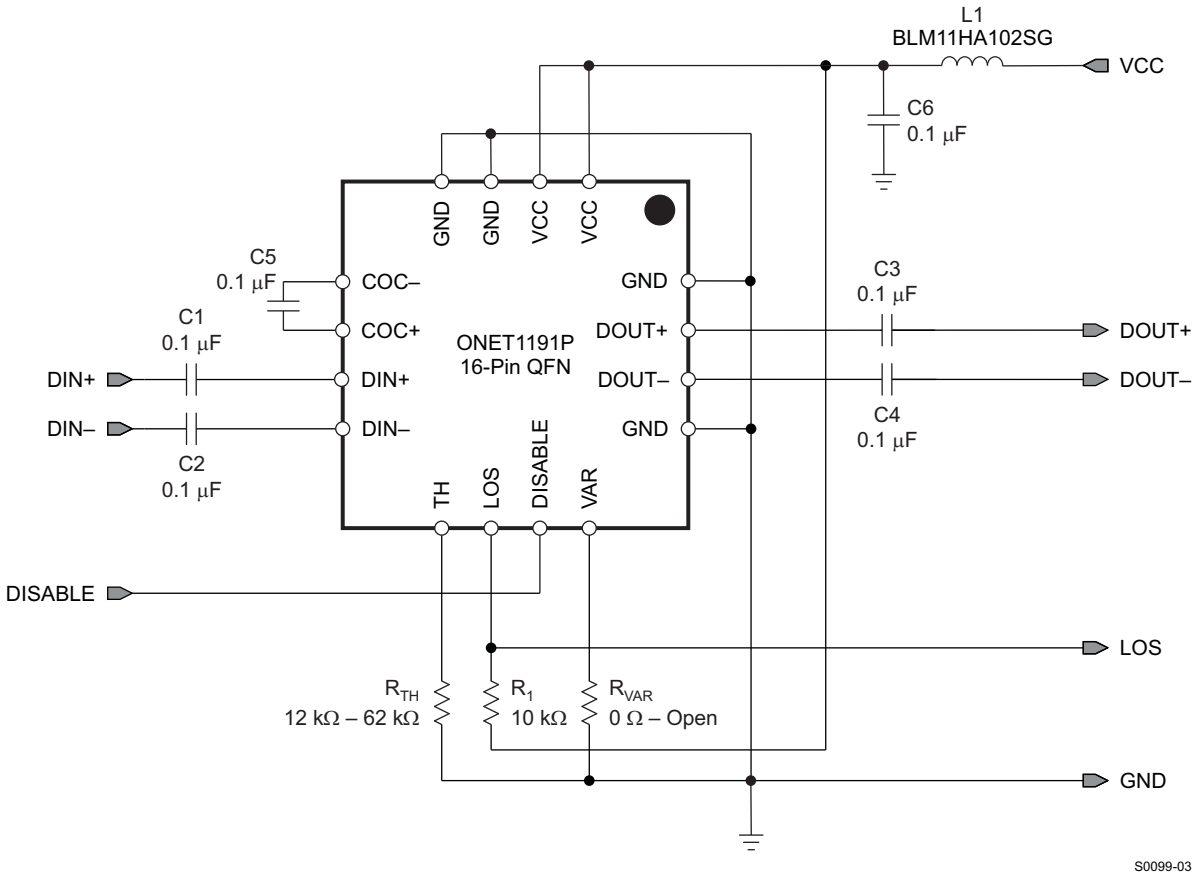


Figure 17. Basic Application Circuit

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package | Pins	Package qty | Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
ONET1191PRGTT	Obsolete	Production	VQFN (RGT) | 16	-	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	191P

(1) **Status:** For more details on status, see our product life cycle.

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

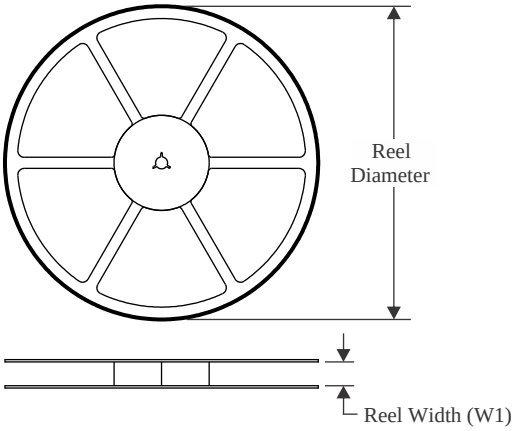
Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

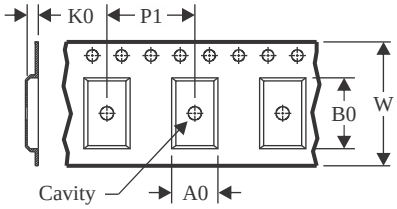
In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

TAPE AND REEL INFORMATION

REEL DIMENSIONS

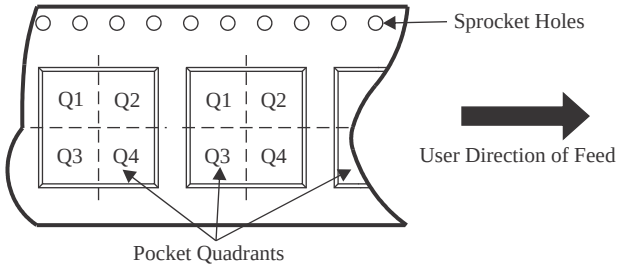


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

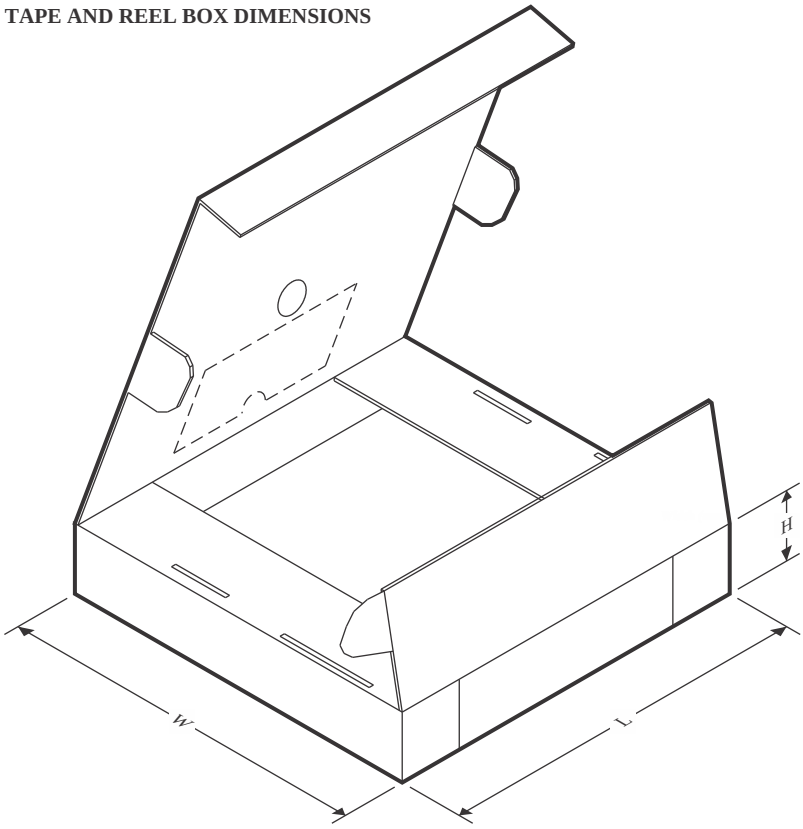
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
ONET1191PRGTT	VQFN	RGT	16	0	180.0	12.4	3.3	3.3	1.1	8.0	12.0	Q2

TAPE AND REEL BOX DIMENSIONS

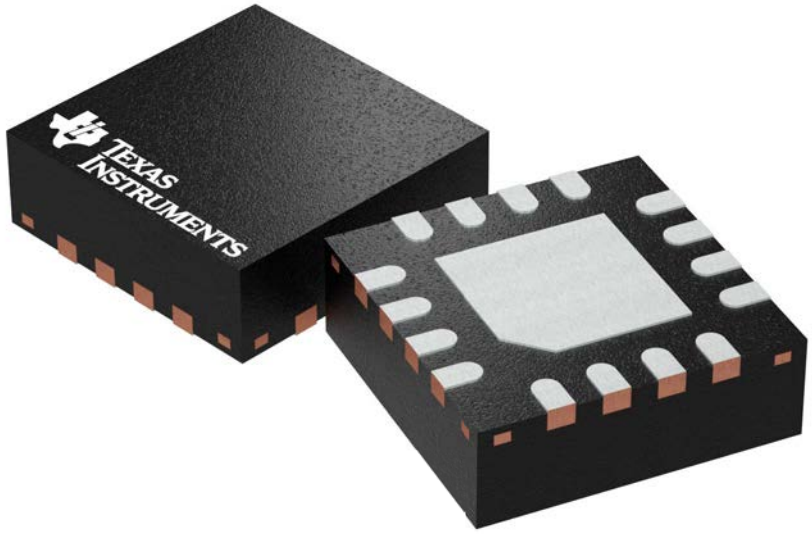


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
ONET1191PRGTT	VQFN	RGT	16	0	210.0	185.0	35.0

RGT 16 VQFN - 1 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



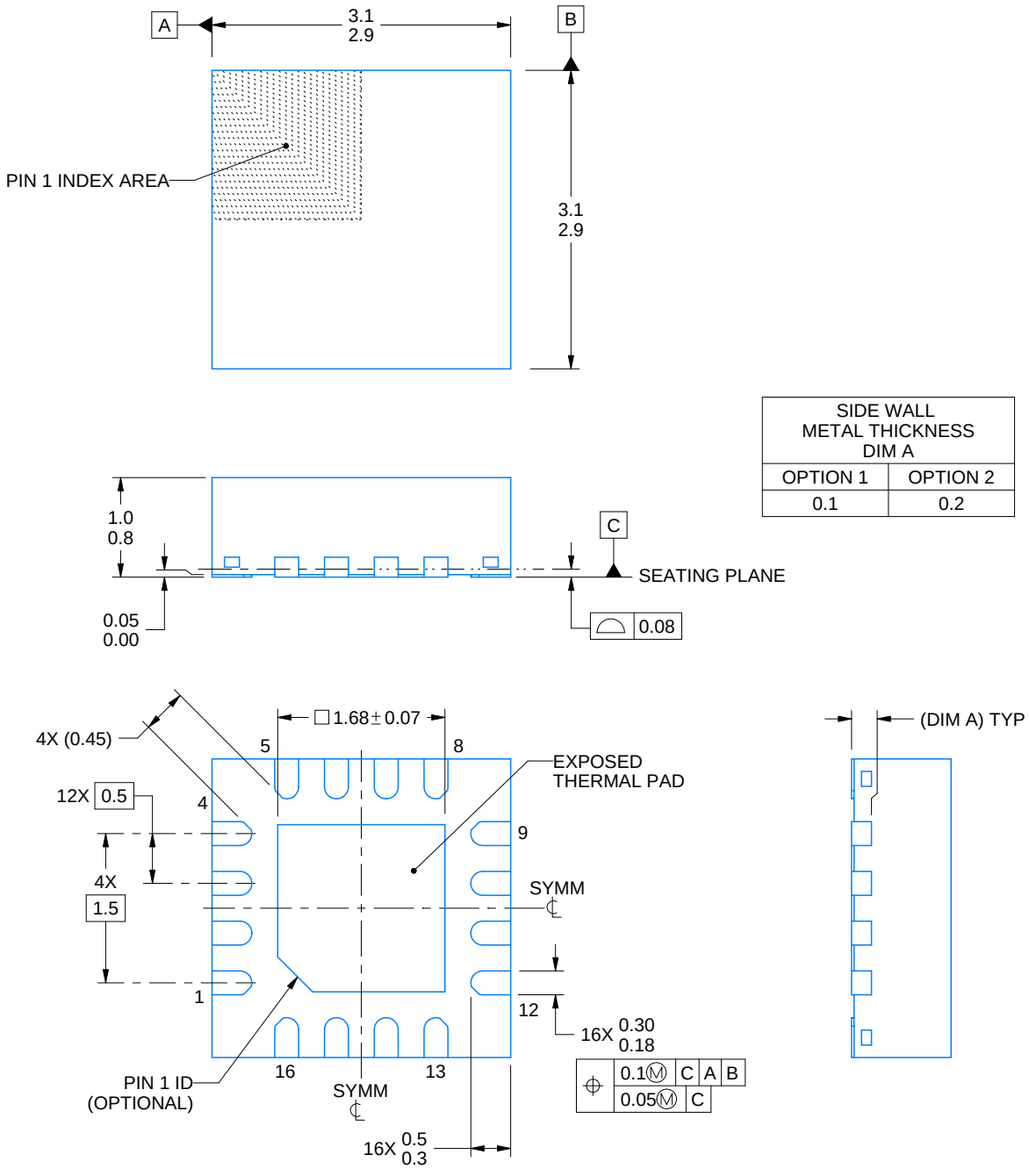
Images above are just a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.

PACKAGE OUTLINE

RGT0016C

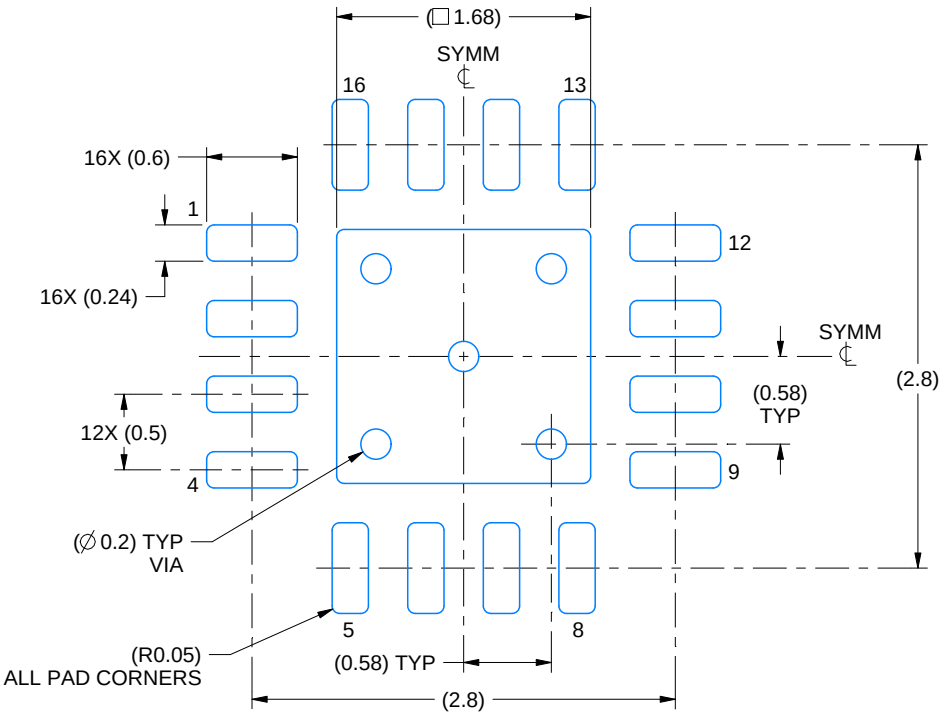
VQFN - 1 mm max height

PLASTIC QUAD FLATPACK - NO LEAD

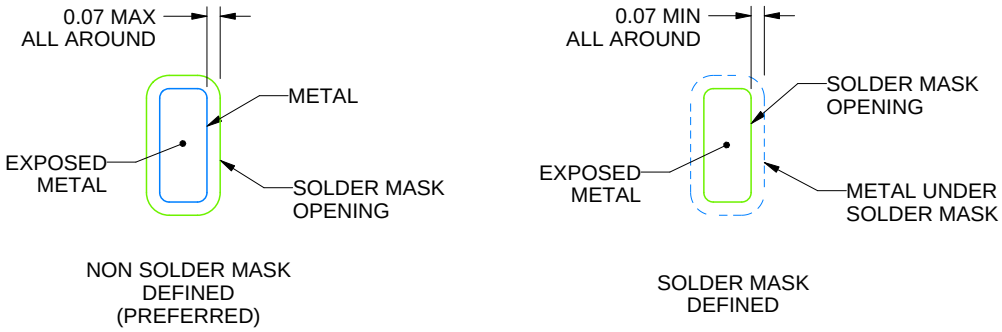


NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pad must be soldered to the printed circuit board for thermal and mechanical performance.



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:20X

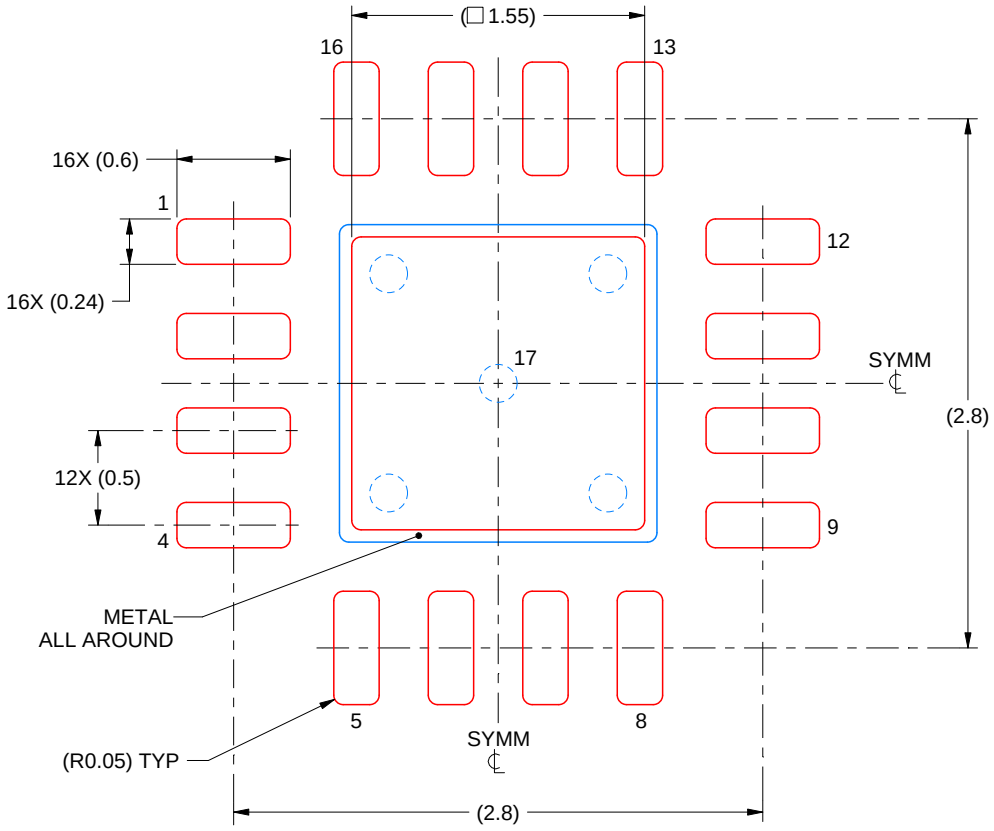


SOLDER MASK DETAILS

4222419/E 07/2025

NOTES: (continued)

4. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/slua271).
5. Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL

EXPOSED PAD 17:
85% PRINTED SOLDER COVERAGE BY AREA UNDER PACKAGE
SCALE:25X

4222419/E 07/2025

NOTES: (continued)

6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATASHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES “AS IS” AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, regulatory or other requirements.

These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you fully indemnify TI and its representatives against any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI’s products are provided subject to TI’s Terms of Sale, TI’s General Quality Guidelines, or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI’s provision of these resources does not expand or otherwise alter TI’s applicable warranties or warranty disclaimers for TI products. Unless TI explicitly designates a product as custom or customer-specified, TI products are standard, catalog, general purpose devices.

TI objects to and rejects any additional or different terms you may propose.

Copyright © 2026, Texas Instruments Incorporated

Last updated 10/2025